

REFERENCES

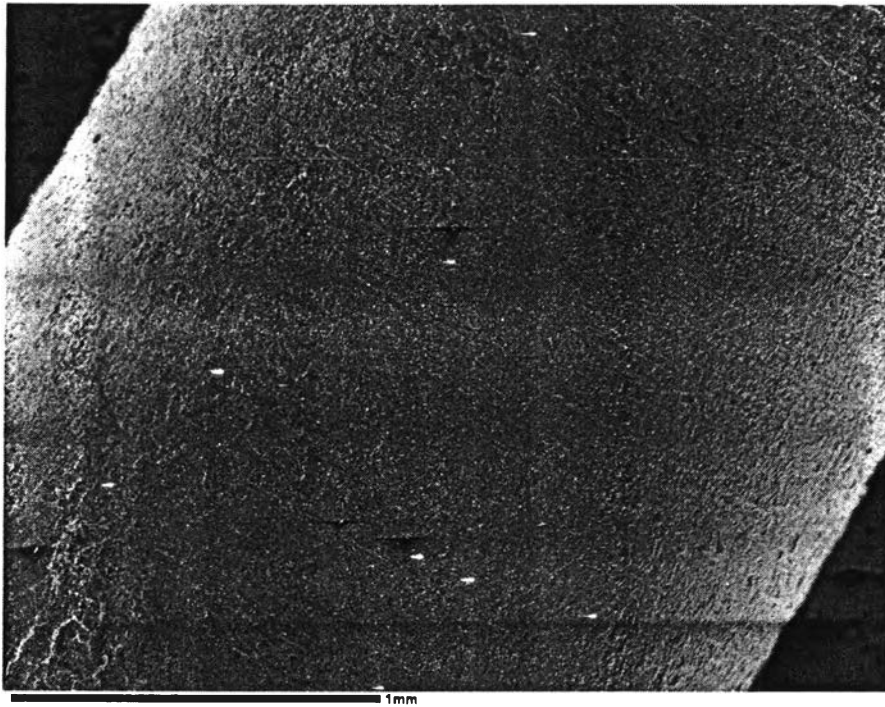
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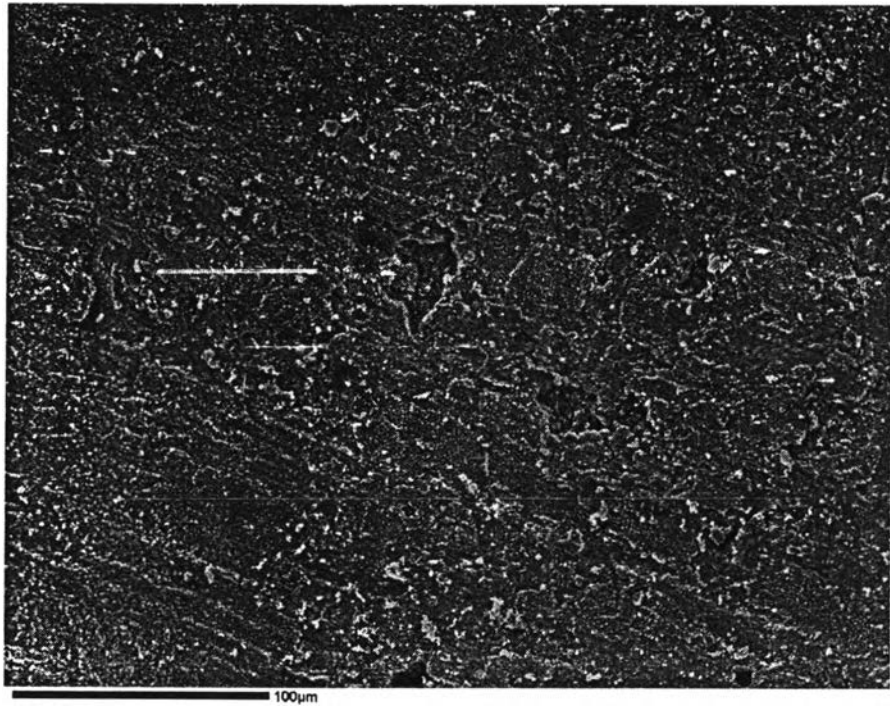
APPENDICES

Appendix A Scanning Electron Microscope Photographs

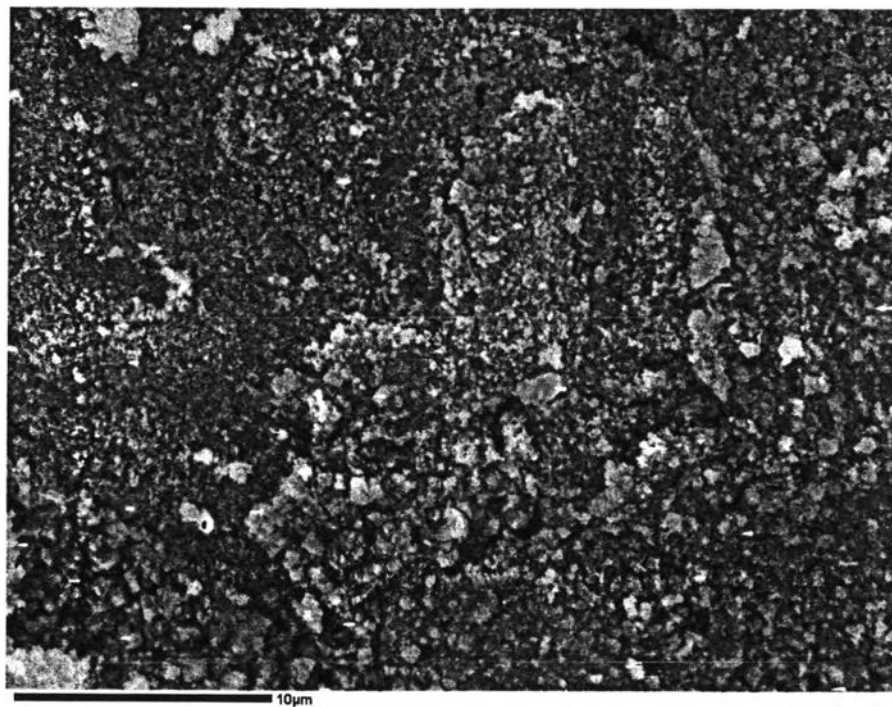
A.1 Scanning Electron Microscope Photographs for A106B Carbon Steel



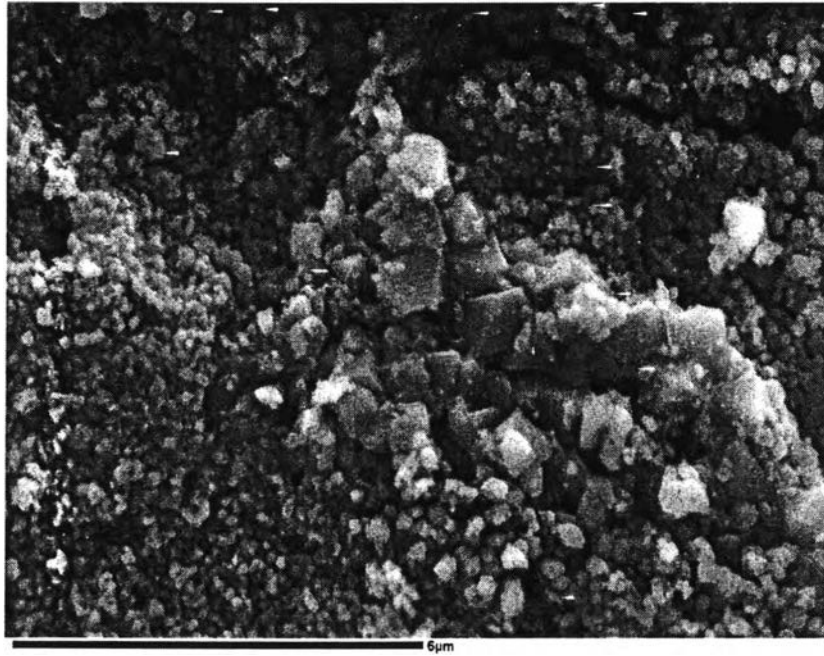
(a) At 50X magnification



(b) At 350X magnification

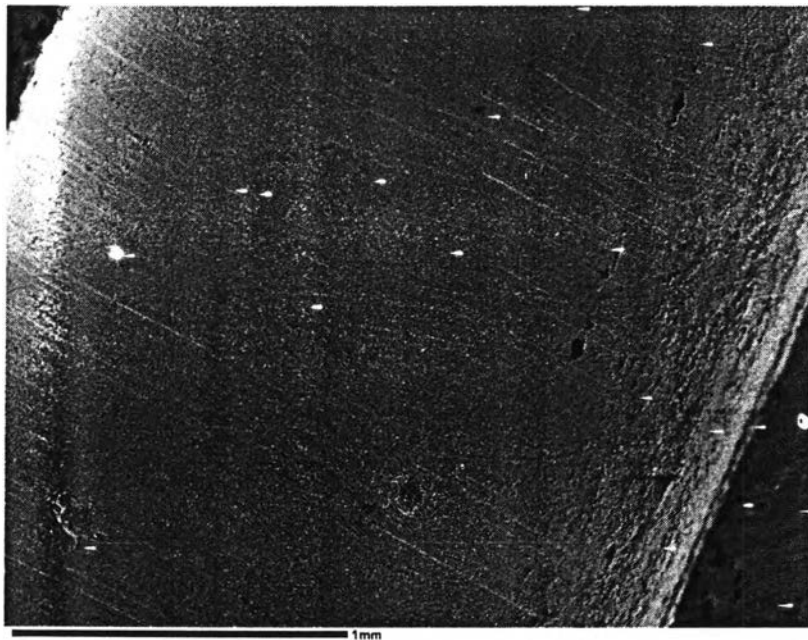


(c) At 3,500X magnification



(d) At 10,000X magnification

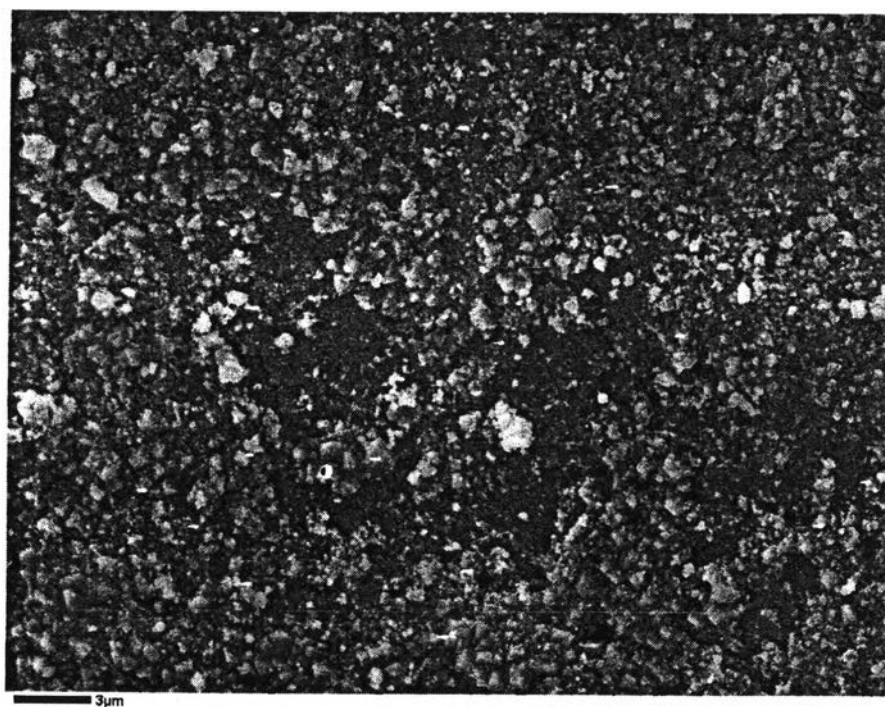
A.2 Scanning Electron Microscope Photographs for Qinshan Steel



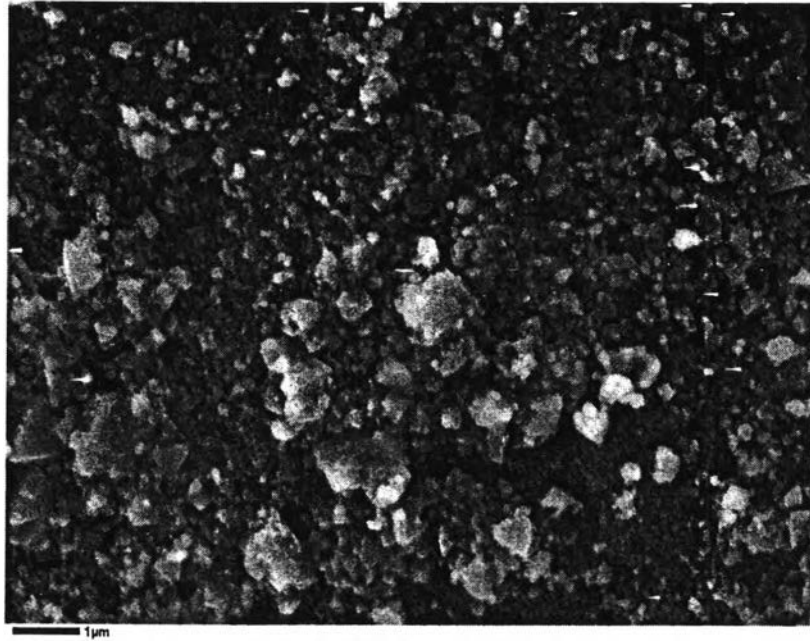
(a) At 50X magnification



(b) At 350X magnification

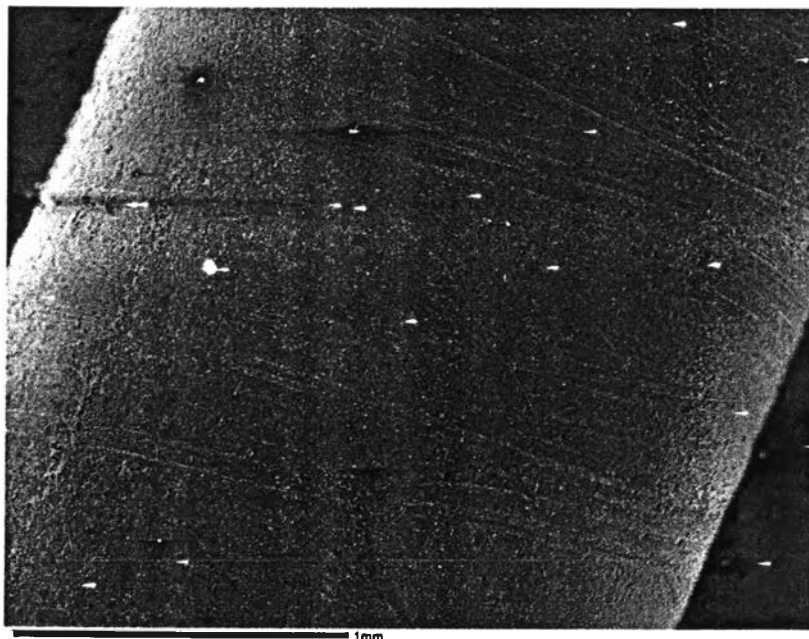


(c) At 3,500X magnification

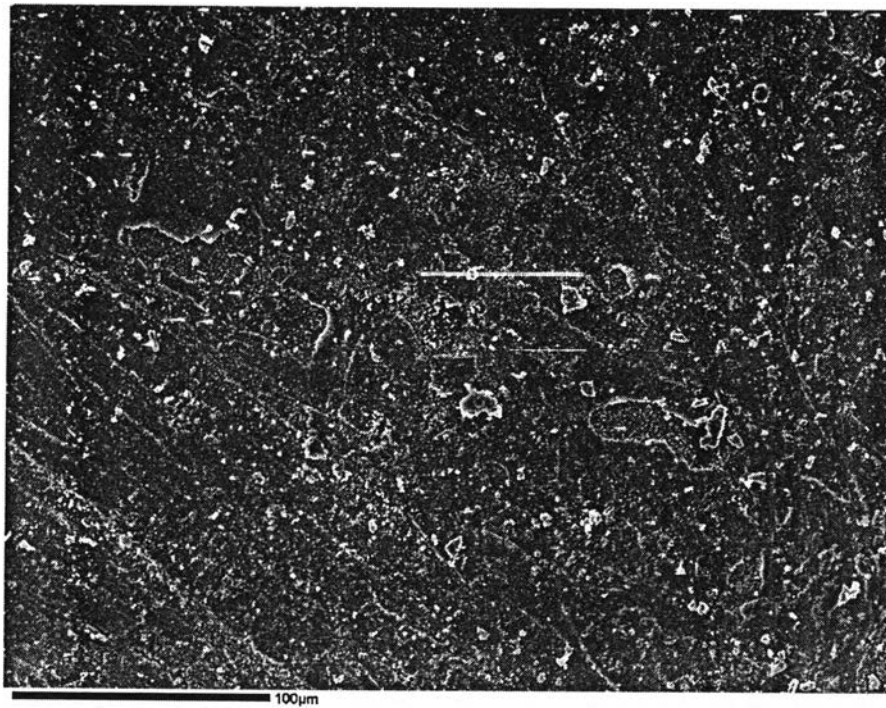


(d) At 10,000X magnification

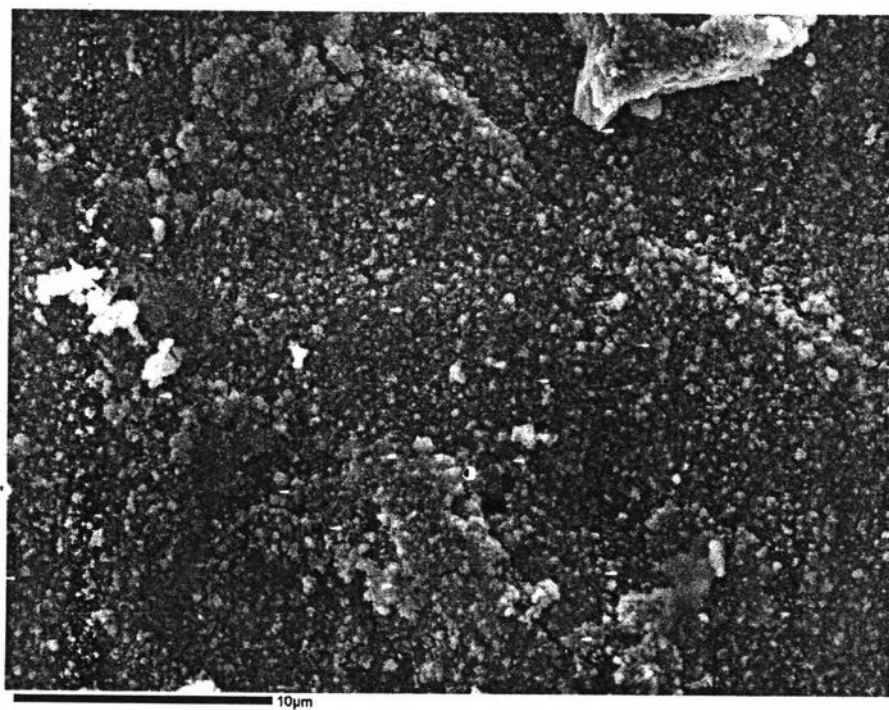
A.3 Scanning Electron Microscope Photographs for 2.5%Cr/1.0%Mo Steel



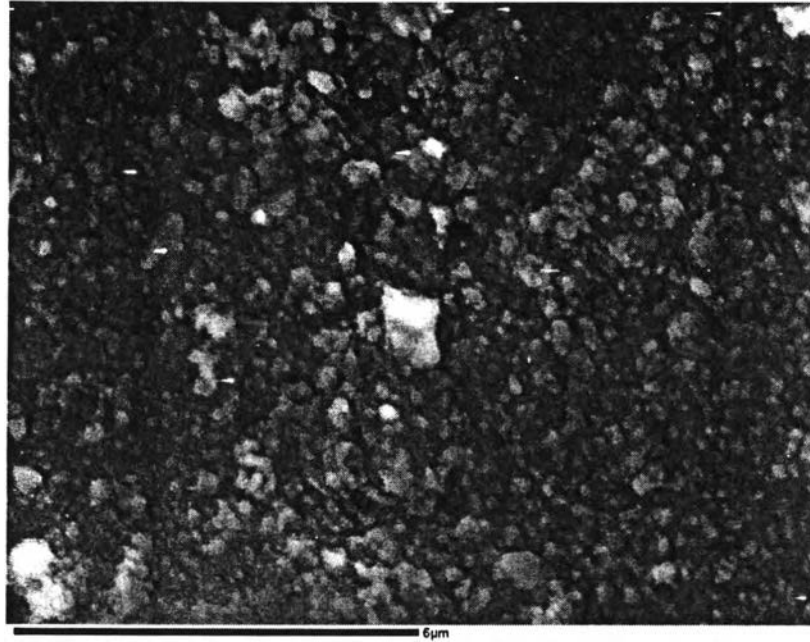
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(b) At 350X magnification

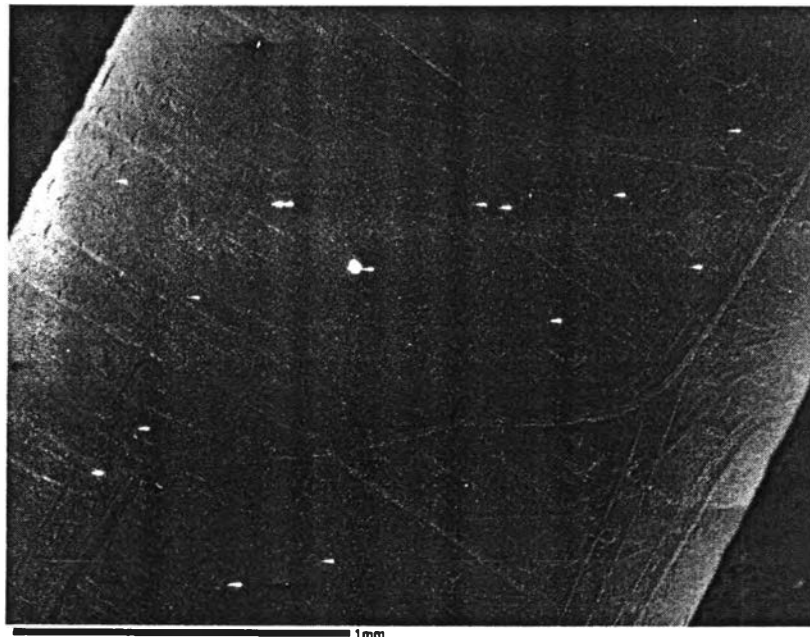


(c) At 3,500X magnification

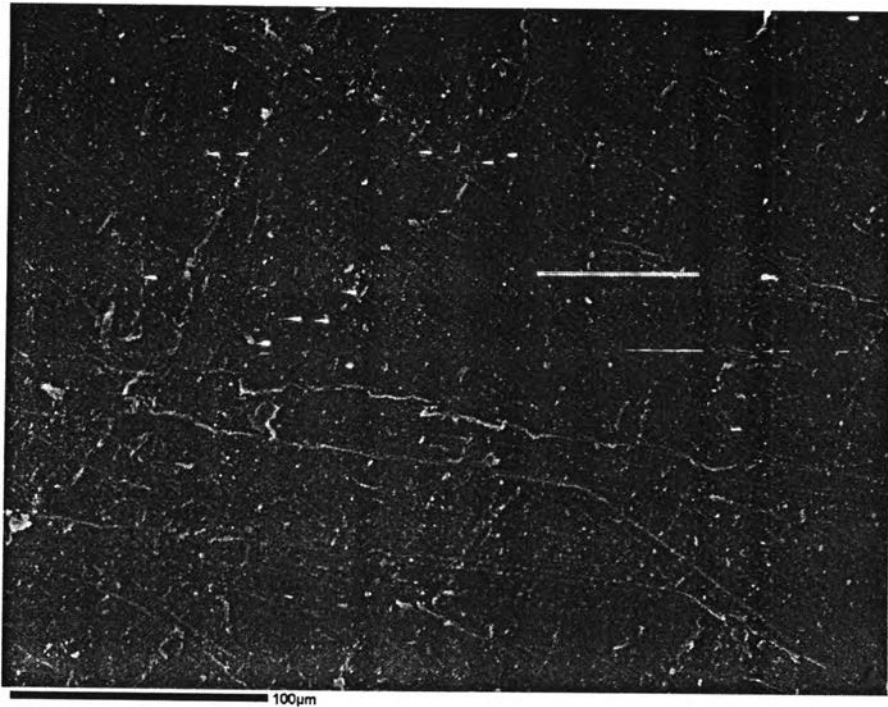


(d) At 10,000X magnification

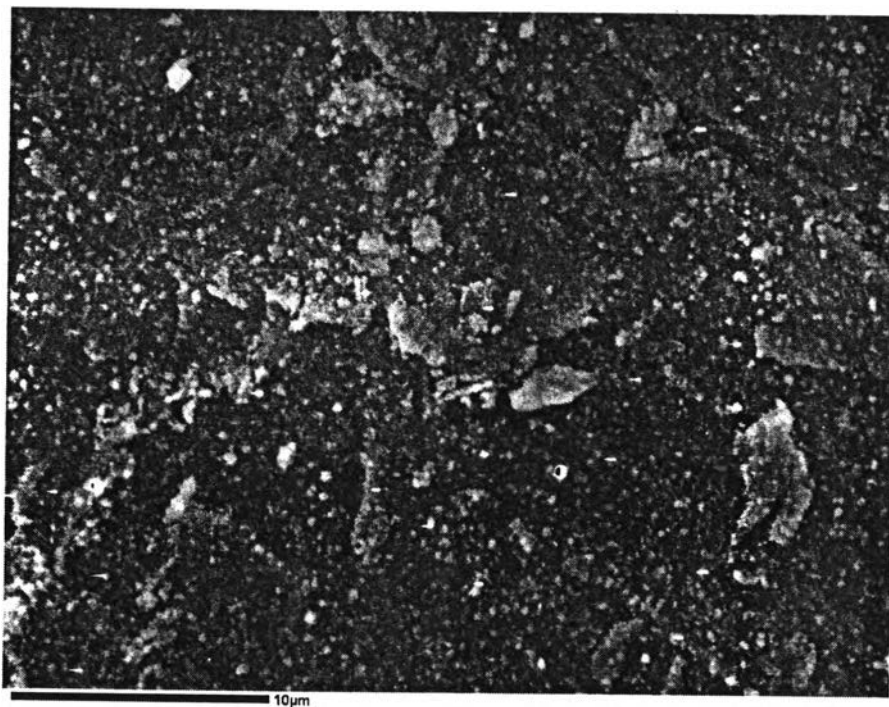
A.4 Scanning Electron Microscope Photographs for 304 Stainless Steel



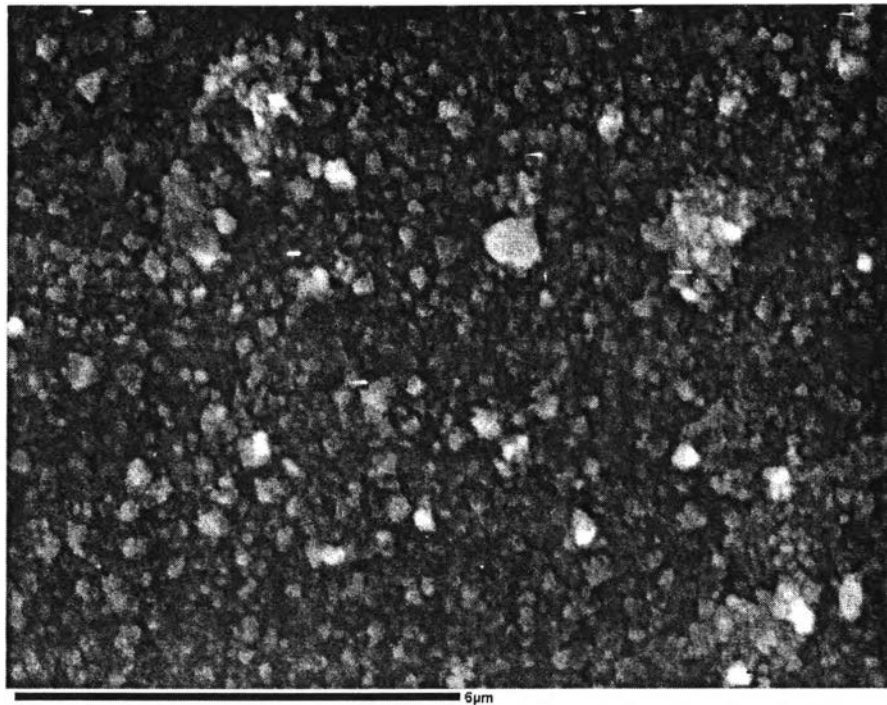
(a) At 50X magnification



(b) At 350X magnification



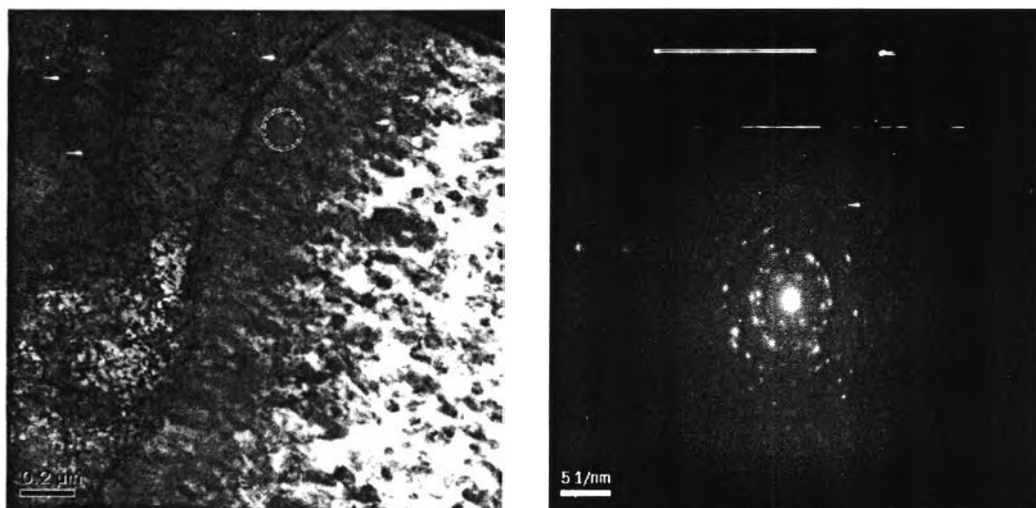
(c) At 3,500X magnification



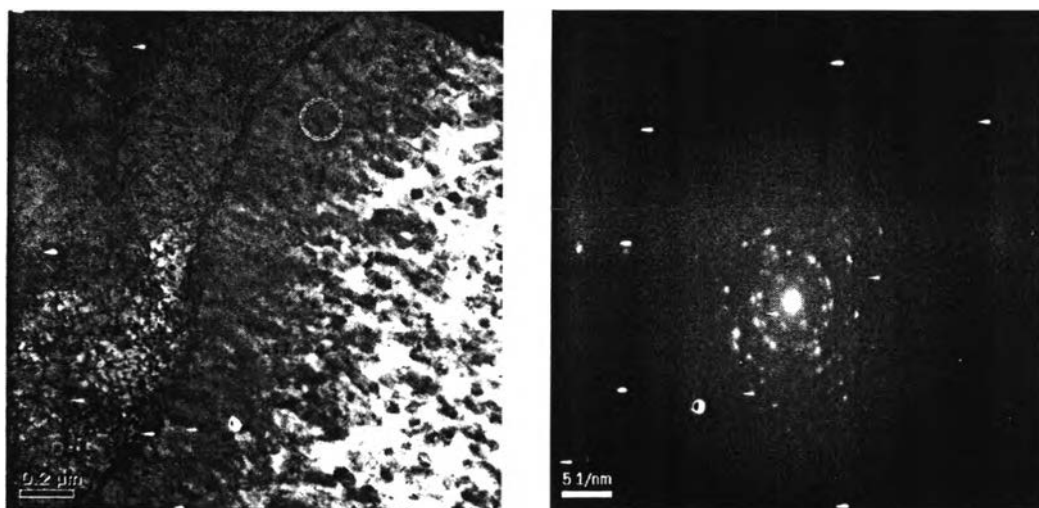
(d) At 10,000X magnification

Appendix B Electron Diffraction Patterns

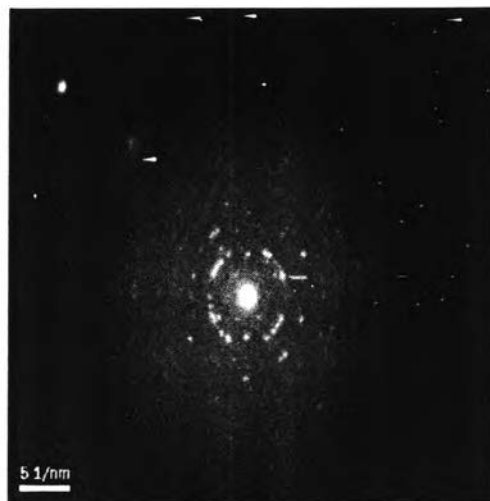
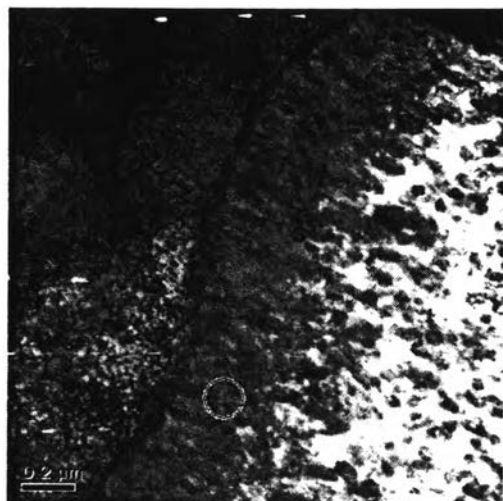
B.1 Electron Diffraction Patterns for A106B Carbon Steel



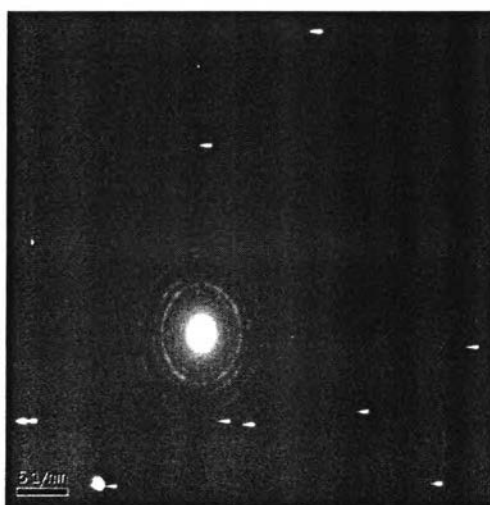
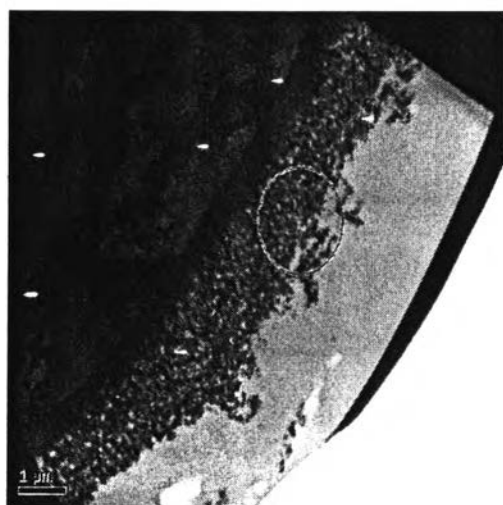
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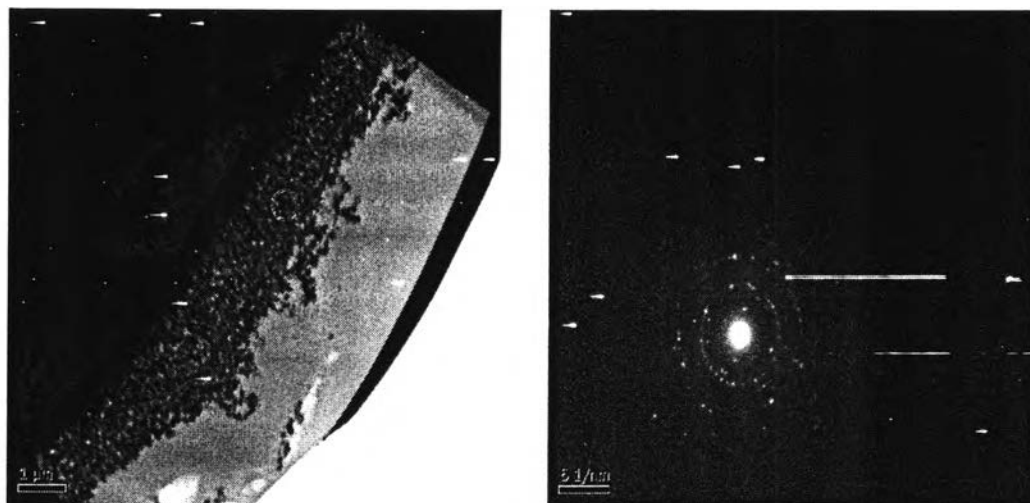
(b) A106B_IN_2



(c) A106B_IN_3

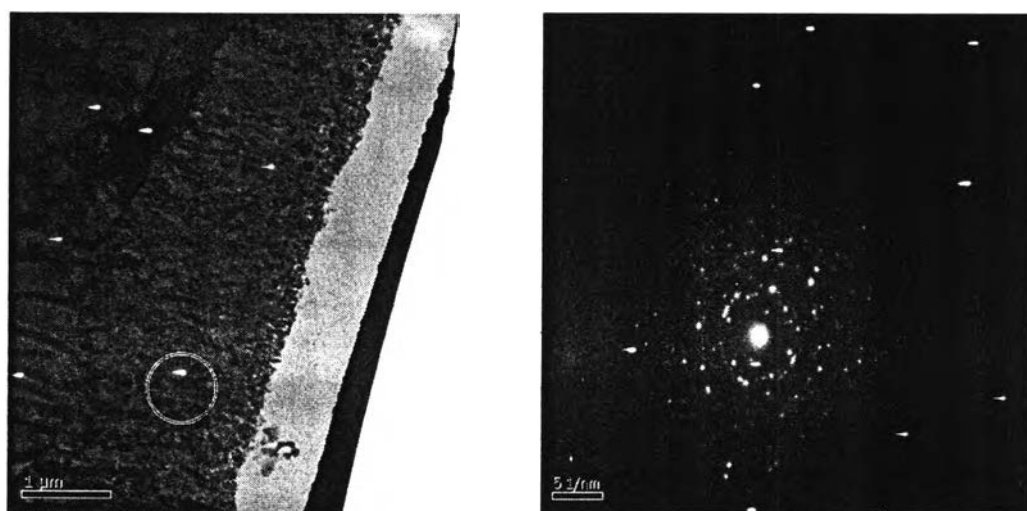


(d) A106B_OUT_1

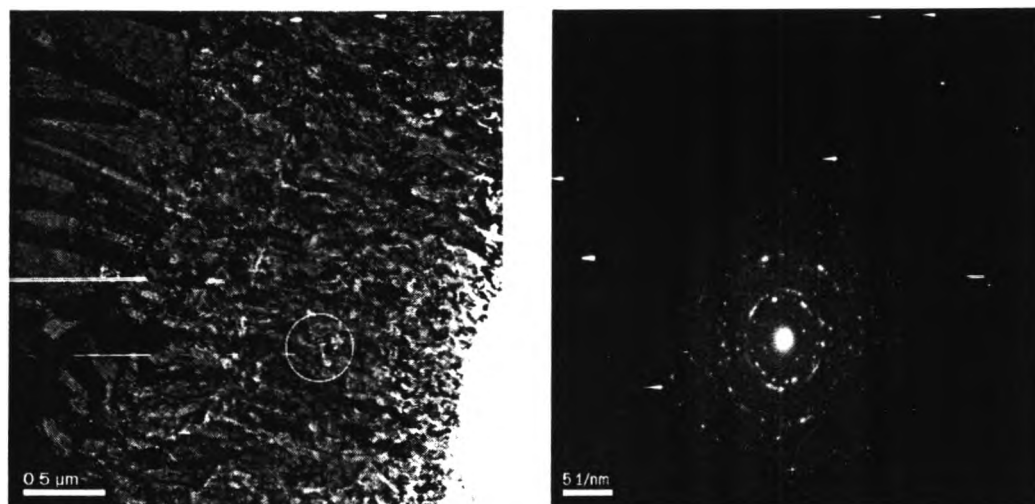


(e) A106B_OUT_2

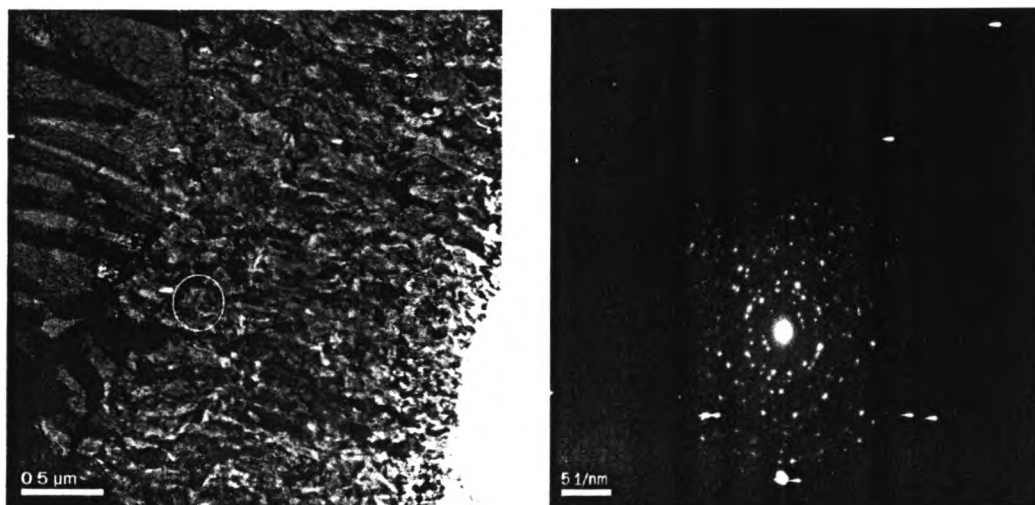
B.2 Electron Diffraction Patterns for Qinshan Steel



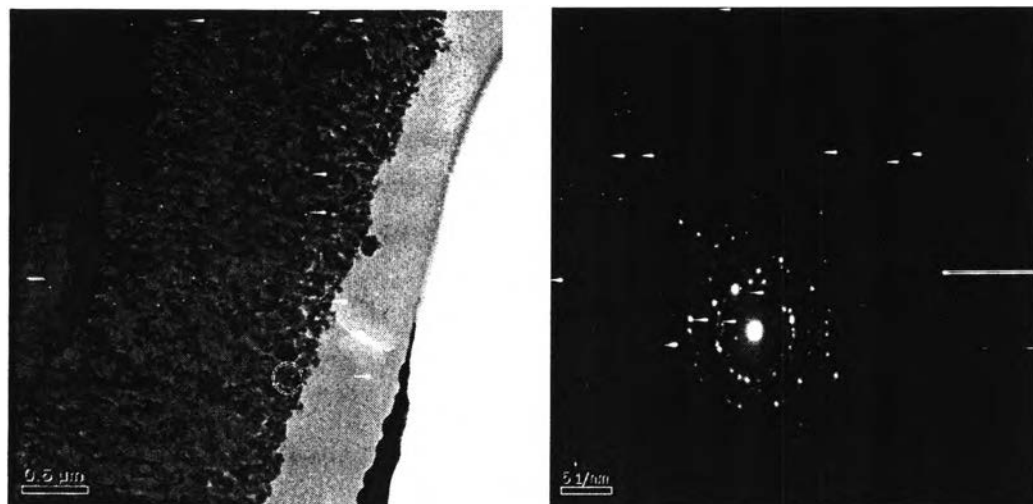
(a) Qinshan_IN_1



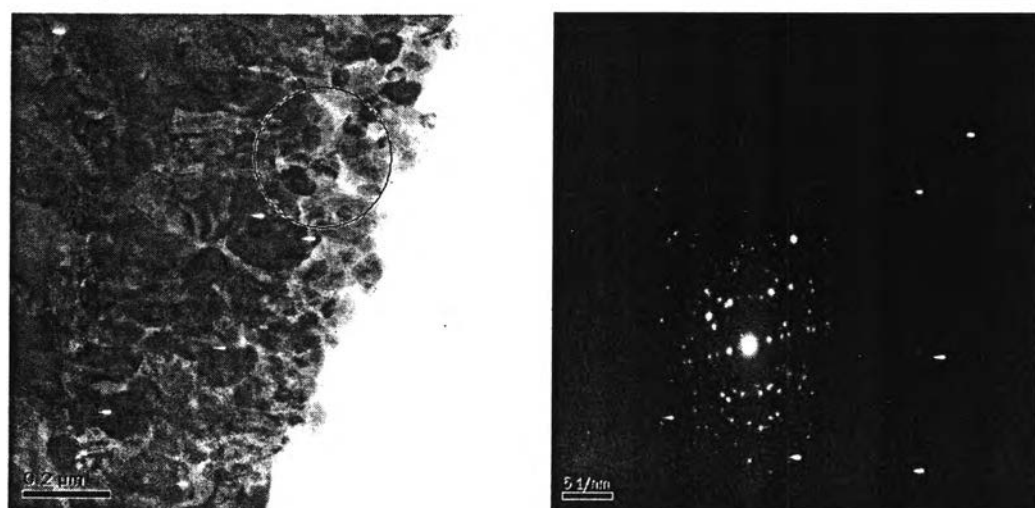
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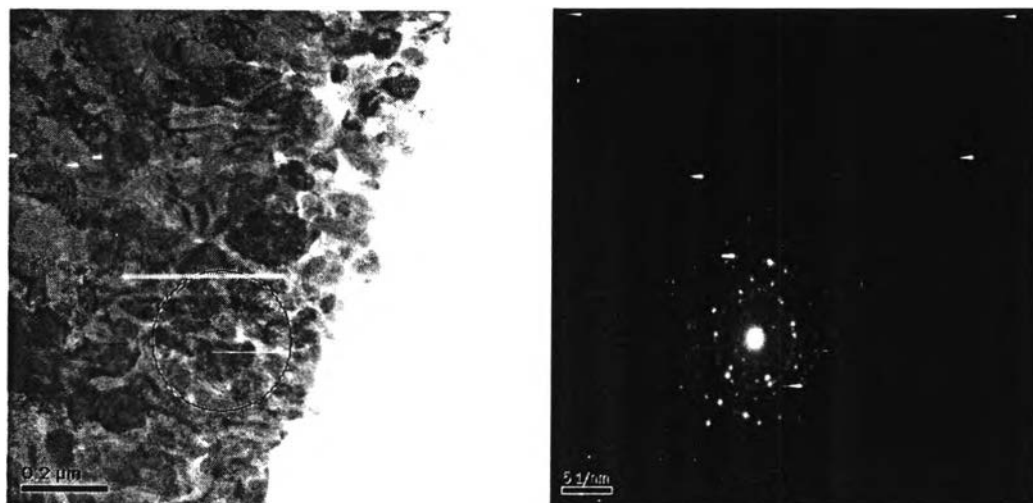
(c) Qinshan_IN_3



(d) Qinshan_OUT_1

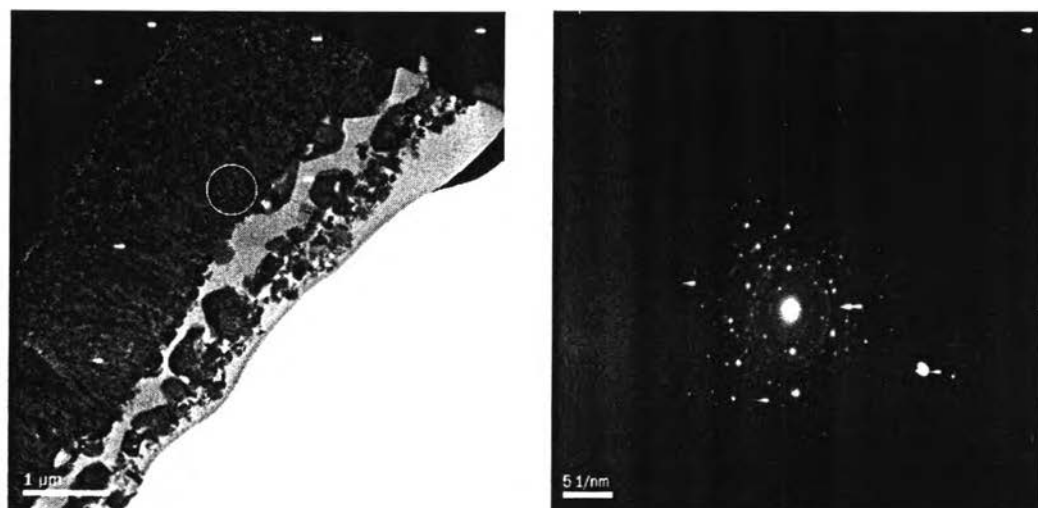


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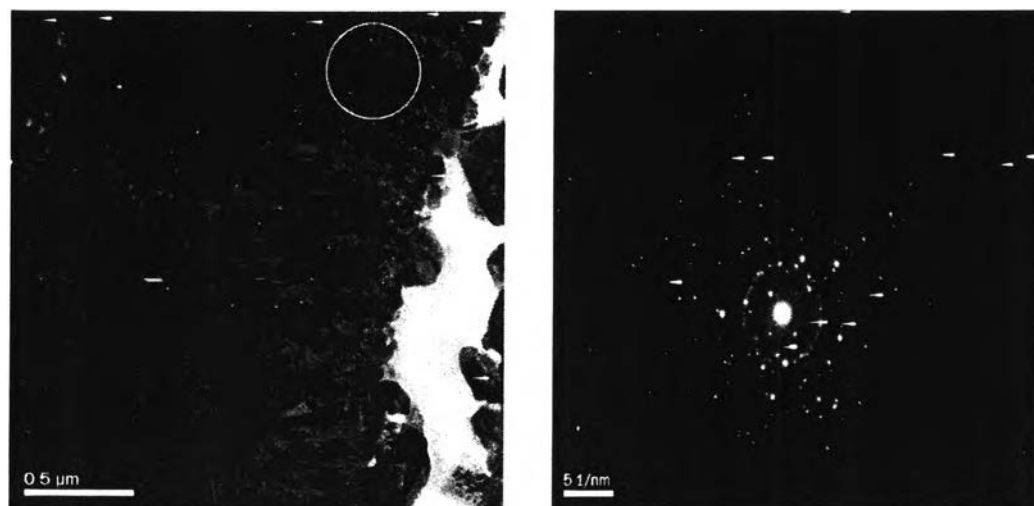


(f) Qinshan_OUT_3

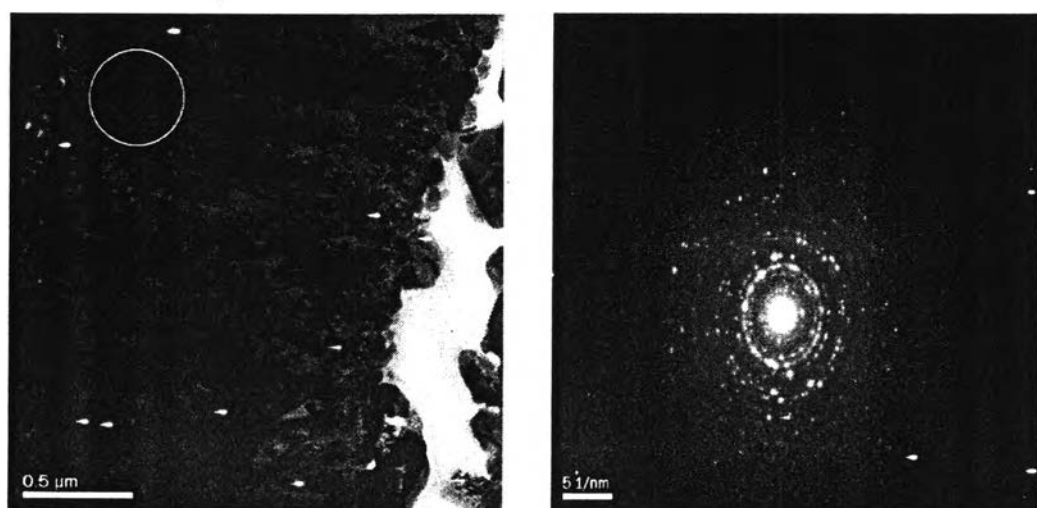
B.3 Electron Diffraction Patterns for 2.5%Cr/1.0%Mo Steel



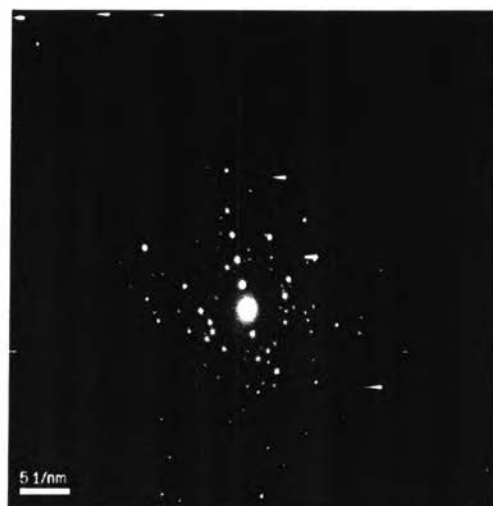
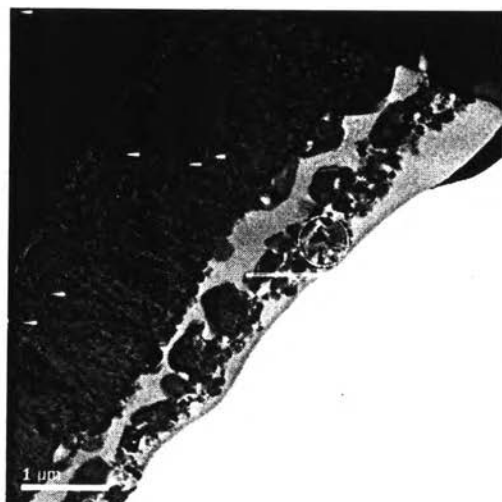
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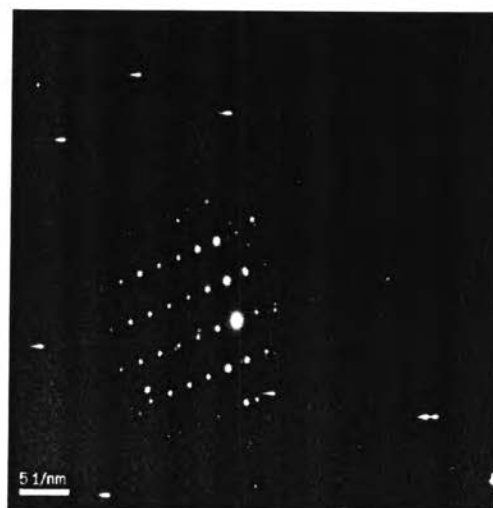
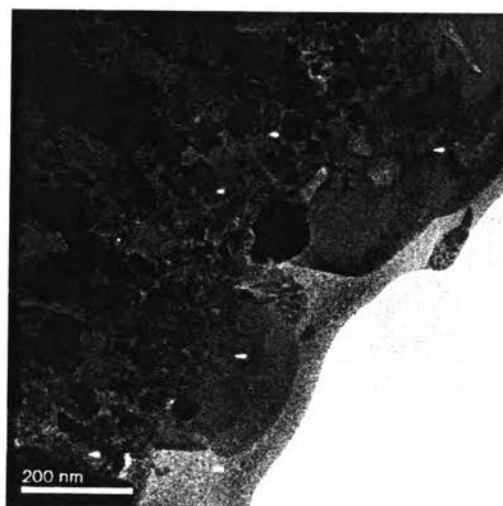
(b) 2.5%Cr_IN_2



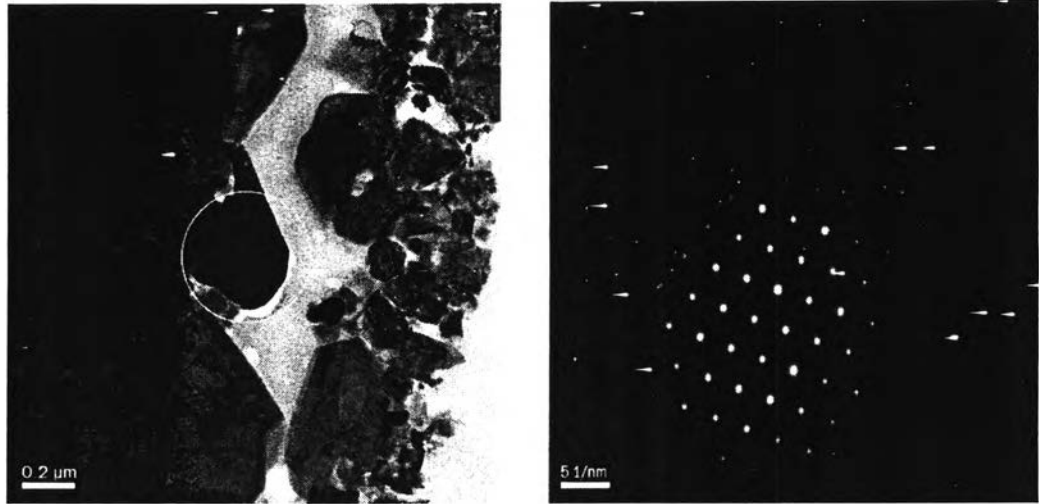
(d) 2.5%Cr_IN_3



(e) 2.5%Cr_OUT_1

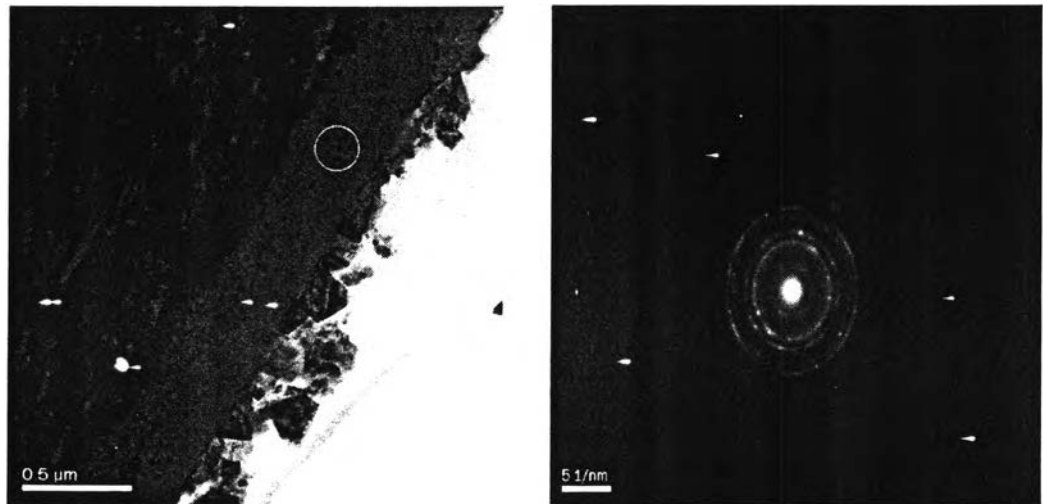


(f) 2.5%Cr_OUT_2

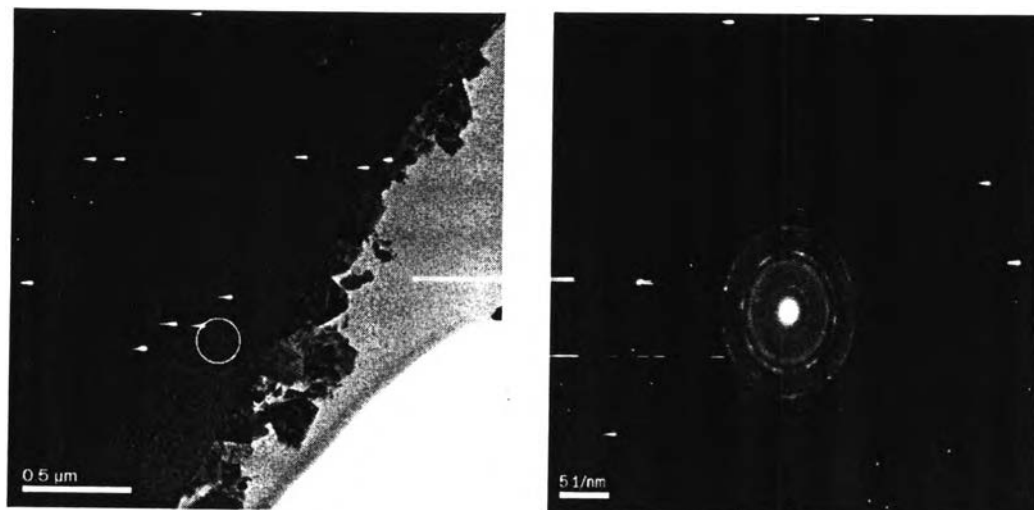


(g) 2.5%Cr_OUT_3

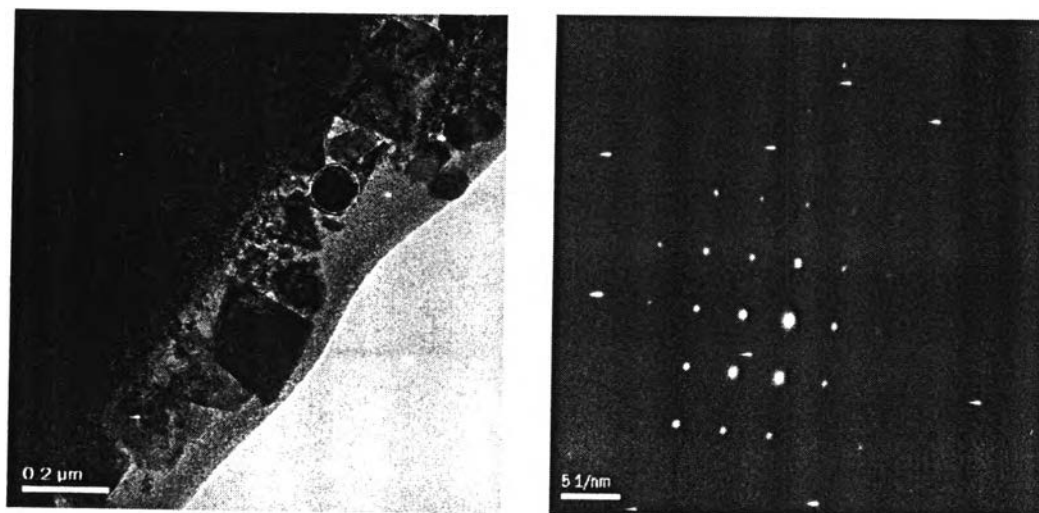
B.4 Electron Diffraction Patterns for 304 Stainless Steel



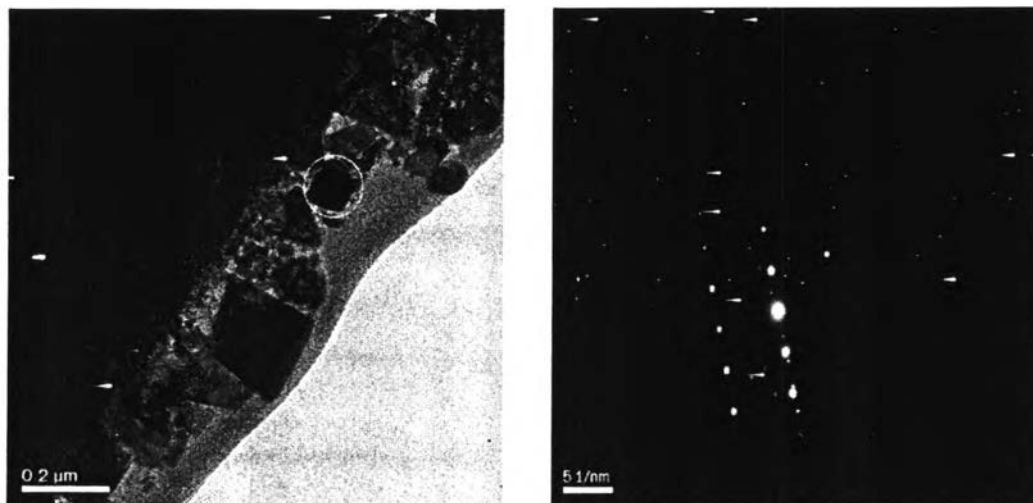
(a) 304SS_IN_1



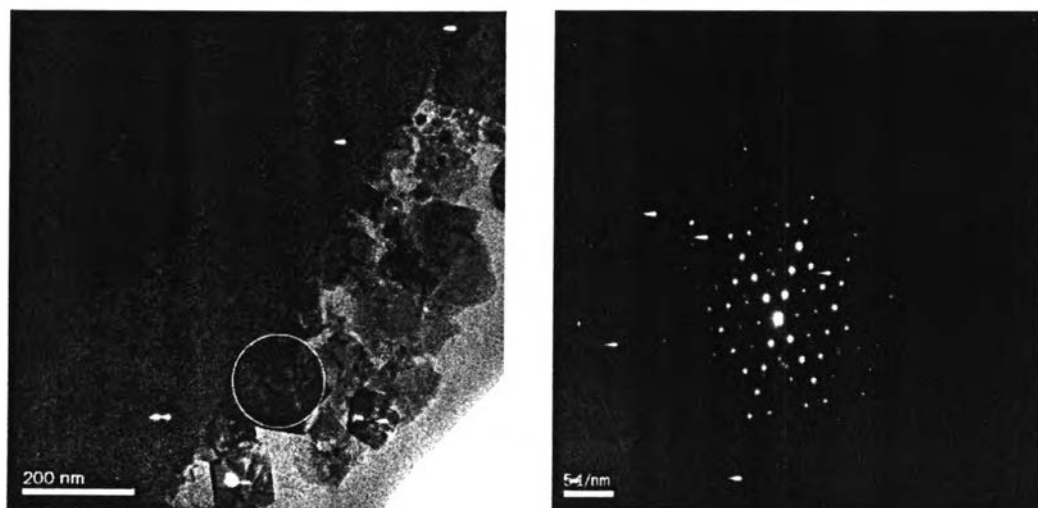
(b) 304SS_IN_2



(d) 304SS_OUT_1



(e) 304SS_OUT_2

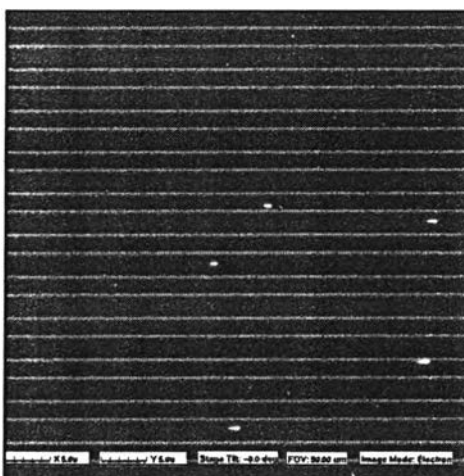


(g) 304SS_OUT_3

Appendix C Lift Out Method

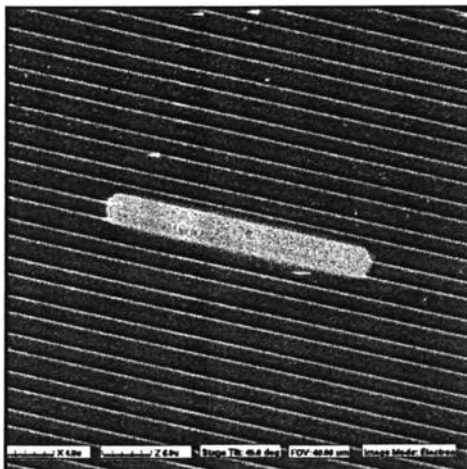
Step 1 Locate the Area of Interest

The location of an area of interest can be done using the FIB microscope's imaging capabilities. Imaging the sample allows the area of interest to be selected visually. For semiconductor devices, the FIB system's precision navigation capabilities can be employed to locate the region of interest with an accuracy that is on the order of microns. The image shows part of a memory array structure of an integrated circuit from which a TEM "lift-out" specimen will be prepared.



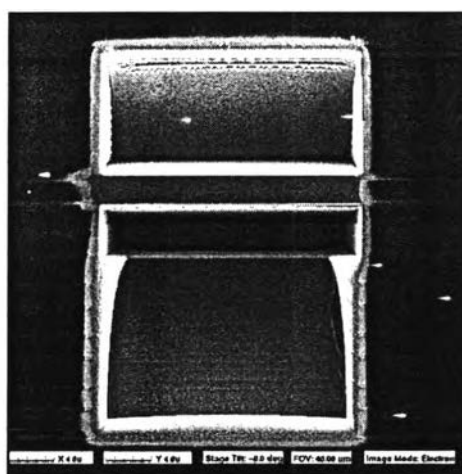
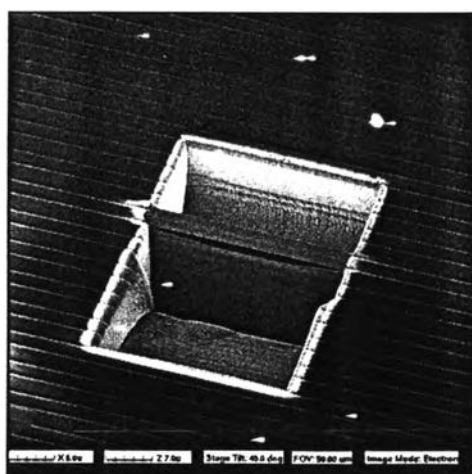
Step 2 FIB-deposit a Protective Tungsten Layer

A layer of FIB-deposited tungsten is placed over the area of interest to prevent milling or multiple image scans from damaging the surface of the TEM specimen cross-section. This step is especially important when surface phenomena on bulk samples are to be analysed. FIB-deposited tungsten provides a fast and precise method for protecting surfaces during FIB procedures.



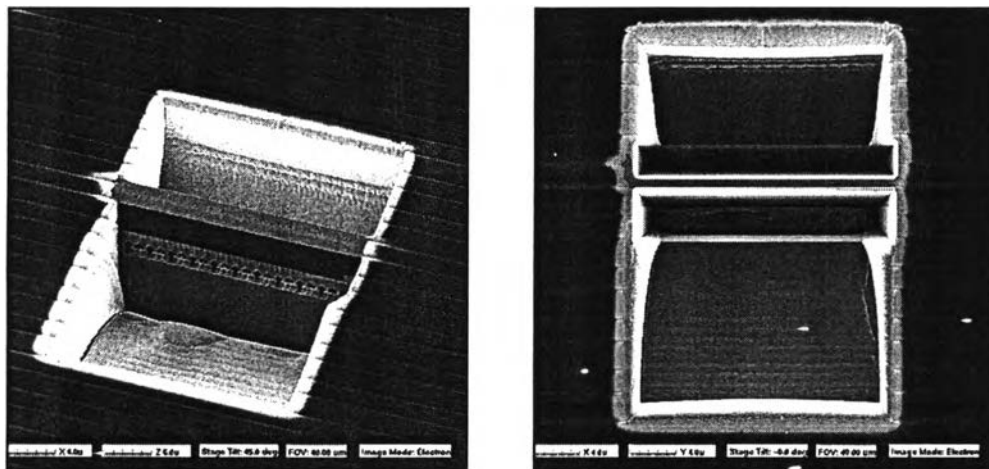
Step 3 Mill Initial Trenches and Rough Polish

Using a large beam current for fast ion milling, two trenches are milled on either side of the tungsten that has been deposited above the area of interest. The trenches here have been milled so as to just touch the tungsten on either side, leaving a wall of material in the centre that is approximately two microns thick. The trenches themselves are approximately twenty microns wide, fourteen microns long and ten to fifteen microns deep.



Step 4 Thin the Central Membrane

A smaller beam current is used to further thin the central membrane between the two trenches to a thickness of approximately 1 micrometer. Because milling at a sharp angle, or on an edge, enhances the speed and depth of the mill, the trenches are now stepped, with their deepest points being on either side of the central membrane. One micron is the nominal thickness at which it is recommended to proceed to the next step in the specimen preparation.

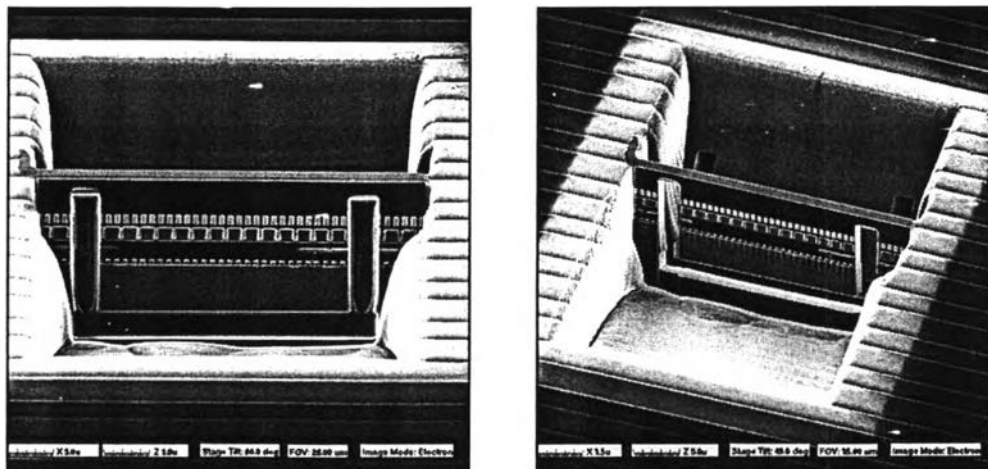


Step 5 Perform "Frame Cuts" on Central Membrane

The bulk sample and the area of interest are tilted to a steep angle, commonly 45° or 60° . Three cuts are made to the central membrane, framing the area of interest. Inside these cuts, the membrane will be ion polished until it is electron transparent. Typically, the membrane is left attached to the bulk at its top two corners. This provides structural strength and stability to the membrane.

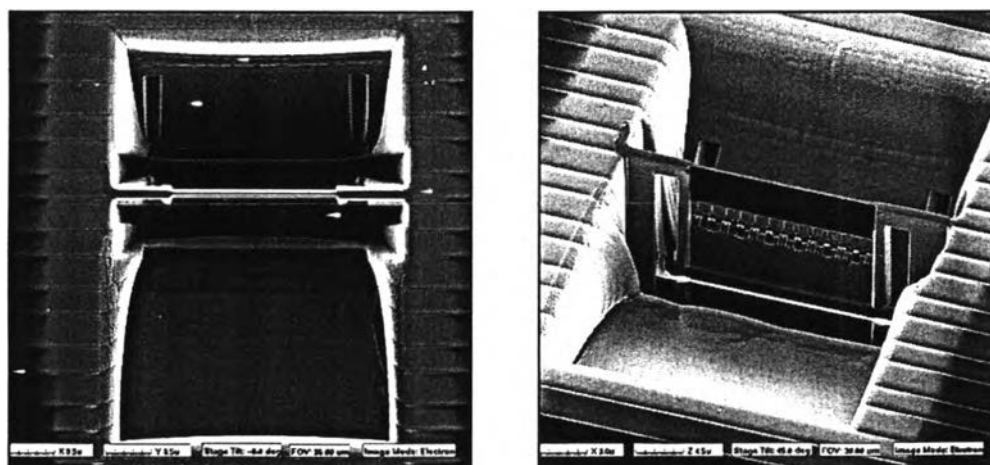
Some damage is done to the membrane by tilting and imaging its face. However, since the penetration depth is on the order of nanometers for any given material, any damage done to the cross-section is restricted to essentially the surface of the sample. During the course of the next few steps in the procedure, more than the first two hundred nanometers of material are polished away, ensuring that any

damage to the electron transparent membrane as a result of imaging is not present in the final specimen.



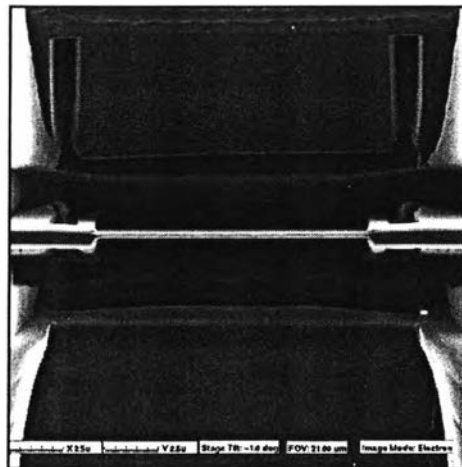
Step 6 "Polish Mills" to Near Nominal Thickness

The beam current is reduced again, and the membrane is ion polished on both sides to a nominal thickness of approximately 0.3 micrometers. At this point, the membrane is very close to being finished. The minimal beam current associated with this step in the procedure leaves the membrane with almost no trace of the ion polish. However, for most materials, 300 nanometers is still much too thick to be electron transparent. So the membrane still requires another very careful, very gentle polishing step.



Step 7 Polish for Electron Transparency of Membrane

The last polishing step, again reducing the beam current, brings the membrane to a thickness of between 120 and 50 nanometers. At these thicknesses, the membrane is electron transparent, and will clearly display the cross-section of the area of interest in a TEM. Milling on this nanometer scale demonstrates the precision that FIB microscope-micromachining systems are capable of attaining. This site specificity and precision make FIB systems very useful tools for TEM specimen preparation and any other milling on a microscopic scale.



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